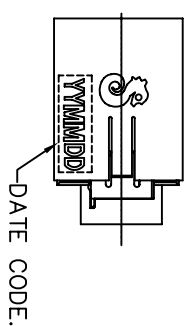
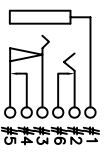


RECOMMENDED PCB LAYOUT  
SOLDER SIDE  
(TOLERANCE: ±0.05)



- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
  - CONTACT RESISTANCE: 30mΩ MAX.
  - DIELECTRIC VOLTAGE WITHSTAND:  
500V AC FOR ONE MINUTE.
  - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20C±2C IN TEMP., 60-70% IN HUMIDITY.
  - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
  - INSERTION FORCE: 0.4 - 3kg.
  - WITHDRAWAL FORCE: 0.3 - 2kg.
  - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
  - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
  - MARKING: MARK "G.P." ON TOP OF CONNECTOR.
  - TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE"
  - GREEN PRODUCT IDENTIFICATION MARK IN JACK: G.P. PASS
  - GREEN PRODUCT IDENTIFICATION LABEL IN PACKING: G.P. PASS
  - FOR LEAD-FREE PROCESS.
  - PACKING: TAPING REEL.



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK COLOR
B	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK COLOR
C	EARTH	1	COPPER ALLOY 0.3t	SILVER PLATING
D	TIP SPRING	1	COPPER ALLOY 0.25t	SILVER PLATING
E	RING SPRING	1	COPPER ALLOY 0.2t	SILVER PLATING
F	SHUNT TERMINAL-A	1	COPPER ALLOY 0.25t	SILVER PLATING
G	BREAK TERMINAL	1	COPPER ALLOY 0.2t	SILVER PLATING
H	TRANSFER TERMINAL	1	COPPER ALLOY 0.2t	NICKEL PLATING
I	SHIELDING	1	COPPER ALLOY 0.2t	SILVER PLATING

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X :±0.5 X :±2

X.X :±0.3 X.X :±1'

X.XX :±0.2

TITLE	DC POWER JACK
DWN	Lussen 4/24-06
CHKD	Song 4/24-06
APVD	Dowl 4/24-06
PART NO.	2SJ-T820-012
SCALE:	4/1
UNIT:	mm
SIZE:	A3
SHEET:	1 OF 1
REV:	A

Singatron Enterprise Co., Ltd.  
信音企業股份有限公司

CUSTOMER COPY(SZ)

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO: 20060407-1-S	Lussen	4/24-06